

L Number	Hits	Search Text	DB	Time stamp
-	164	(710/317).CCLS.	USPAT; US-PGPUB	2004/01/09 12:03
-	18	((710/317).CCLS.) and analog and digital	USPAT; US-PGPUB	2003/12/19 14:17
-	37232	microcontroller	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/19 13:51
-	14360	microcontroller and analog and digital	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/19 13:51
-	2326	(microcontroller and analog and digital) and (wirebond or "wire bond" or pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/19 13:52
-	1714	((microcontroller and analog and digital) and (wirebond or "wire bond" or pad)) and processor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/19 13:52
-	1459	((microcontroller and analog and digital) and (wirebond or "wire bond" or pad)) and processor) and (crossbar or switch\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/19 13:55
-	1458	((microcontroller and analog and digital) and (wirebond or "wire bond" or pad)) and processor) and (crossbar or switch\$5)	USPAT; US-PGPUB	2003/12/19 13:56
-	37232	microcontroller	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/19 14:11
-	316838	analog same digital	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/19 14:11
-	13231	microcontroller and (analog same digital)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/19 14:12
-	0	((710/317).CCLS.) and wirebond	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/19 14:12
-	8	(microcontroller and (analog same digital)) and wirebond	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/19 14:12
-	62	(microcontroller and (analog same digital)) and (wirebond or "wire bond")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/19 14:13
-	55	((microcontroller and (analog same digital)) and (wirebond or "wire bond")) and (processor or microprocessor or cpu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/19 14:14

-	48	((microcontroller and (analog same digital)) and (wirebond or "wire bond")) and (processor or microprocessor or cpu) and (switch\$4 or crossbar or "cross bar")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/19 14:16
-	0	((microcontroller and (analog same digital)) and (wirebond or "wire bond")) and (processor or microprocessor or cpu) and (switch\$4 or crossbar or "cross bar")) not microcontroller	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/19 14:16
-	316838	analog same digital	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/19 14:17
-	803	(analog same digital) and (wirebond or "wire bond")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/19 14:17
-	493	((analog same digital) and (wirebond or "wire bond")) and (switch\$4 or crossbar or "cross bar")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/19 14:18
-	301	((analog same digital) and (wirebond or "wire bond")) and (switch\$4 or crossbar or "cross bar")) and (processor or microprocessor or cpu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/19 17:05
-	2	("6144327") or ("5202687").PN.	USPAT; US-PGPUB	2003/12/19 17:06
-	1	("6192431").PN.	USPAT; US-PGPUB	2003/12/22 13:19
-	0	6192431.URPN.	USPAT	2003/12/22 13:15
-	0	6192431.URPN.	USPAT	2003/12/22 13:15
-	6	("5701517"   "5715197"   "5737764"   "5748982"   "5822610"   "5835965").PN.	USPAT	2003/12/22 13:15
-	1649	(257/666).CCLS.	USPAT; US-PGPUB	2003/12/22 13:19
-	1335	((257/666).CCLS.) and (wirebond or "wire bond" or pad)	USPAT; US-PGPUB	2003/12/22 14:01
-	87	((257/666).CCLS.) and (wirebond or "wire bond" or pad) and (processor or cpu)	USPAT; US-PGPUB	2003/12/22 13:21
-	81	((257/666).CCLS.) and (wirebond or "wire bond" or pad) and (processor or cpu) and (switch or select\$6 or configura\$5)	USPAT; US-PGPUB	2003/12/22 13:23
-	64	((257/666).CCLS.) and (wirebond or "wire bond" or pad) and (processor or cpu) and (switch or select\$6 or configurable or reconfigurable or re-configurable)	USPAT; US-PGPUB	2003/12/22 13:23
-	429	((257/666).CCLS.) and (wirebond or "wire bond")	USPAT; US-PGPUB	2003/12/22 14:03
-	43	((257/666).CCLS.) and (wirebond or "wire bond")) and (processor or cpu)	USPAT; US-PGPUB	2003/12/22 14:02
-	482	((257/666).CCLS.) and ((wirebond or "wire bond") next10 (processor or cpu))	USPAT; US-PGPUB	2003/12/22 14:03
-	422718	("wire bond" or wirebond) next10 (processor or cpu)	USPAT; US-PGPUB	2003/12/22 14:04
-	482	("wire bond" or wirebond) next10 (processor or cpu) and ((257/666).CCLS.)	USPAT; US-PGPUB	2003/12/22 14:04
-	17	("wirebond pad" or "wire bond pad") near10 (processor or cpu)	USPAT; US-PGPUB	2003/12/22 14:07
-	48	(wirebond or "wire bond") near10 (processor or cpu)	USPAT; US-PGPUB	2003/12/22 14:08
-	8	((wirebond or "wire bond") near10 (processor or cpu)) same (switch or configura\$6 or select\$6)	USPAT; US-PGPUB	2003/12/22 14:10

-	1	("5563529").PN.	USPAT;	2003/12/22
-	1	("6445242").PN.	US-PGPUB	14:12
-	1133	(257/676).CCLS.	USPAT;	2003/12/22
-	207	"wirebond pad"	US-PGPUB	14:14
-	1183	"wire bond pad"	USPAT;	2003/12/22
-	1351	"wirebond pad" or "wire bond pad"	US-PGPUB	14:15
-	188	("wirebond pad" or "wire bond pad") and processor	USPAT;	2003/12/22
-	2443436	switch\$6 or select\$6 or reconfigurable or re-configurable or configurable	US-PGPUB	14:17
-	0	((("wirebond pad" or "wire bond pad") near10 (processor or cpu)) near10 (switch\$5 or select\$5 or configurable or reconfigurable or re-configurable)	USPAT;	2003/12/22
-	0	((("wirebond pad" or "wire bond pad") near10 (processor or cpu)) same (switch\$5 or select\$5 or configurable or reconfigurable or re-configurable)	US-PGPUB	14:18
-	1	((("wirebond pad" or "wire bond pad") near10 (processor or cpu)) and (switch\$5 or select\$5 or configurable or reconfigurable or re-configurable)	USPAT;	2003/12/22
-	11	((("wirebond pad" or "wire bond pad") near10 (processor or cpu)) and (switch\$5 or select\$5 or configurable or reconfigurable or re-configurable)	US-PGPUB	14:20
-	954	(326/38).CCLS.	USPAT;	2003/12/22
-	2	((326/38).CCLS.) and ("wirebond pad" or "wire bond pad")	US-PGPUB	16:00
-	1058	(326/41).CCLS.	USPAT;	2003/12/22
-	1	((326/41).CCLS.) and ("wirebond pad" or "wire bond pad")	US-PGPUB	16:02
-	319	(257/e23.011).CCLS.	USPAT;	2003/12/22
-	3	((257/e23.011).CCLS.) and ("wirebond pad" or "wire bond pad")	US-PGPUB	16:03
-	65	(257/e23.032).CCLS.	USPAT;	2003/12/22
-	0	((257/e23.032).CCLS.) and ("wirebond pad" or "wire bond pad")	US-PGPUB	16:04
-	534	(257/e23.079).CCLS.	USPAT;	2003/12/22
-	11	((257/e23.079).CCLS.) and ("wirebond pad" or "wire bond pad")	US-PGPUB	16:07
-	401	(710/316).CCLS.	USPAT;	2003/12/22
-	0	((710/316).CCLS.) and ("wirebond pad" or "wire bond pad")	US-PGPUB	16:11
-	164	(710/317).CCLS.	USPAT;	2003/12/22
-	0	((710/317).CCLS.) and ("wirebond pad" or "wire bond pad")	US-PGPUB	16:12
-	82	((326/38).CCLS.) and ((326/41).CCLS.) and (pad and processor or microprocessor)	USPAT;	2003/12/22
-	42	((326/38).CCLS.) and ((326/41).CCLS.) and (pad and (processor or microprocessor))	US-PGPUB	16:27
-	35	((326/38).CCLS.) and ((326/41).CCLS.) and (pad and (processor or microprocessor))) and (configurable or reconfigurable or re-configurable)	USPAT;	2003/12/22
-			US-PGPUB	16:28

-	31	((((326/38).CCLS.) and ((326/41).CCLS.) and (pad and (processor or microprocessor))) and (configurable or reconfigurable or re-configurable)) and switch\$6	USPAT; US-PGPUB	2003/12/22 16:31
-	382	(configurable or reconfigurable or re-configurable) near6 pin	USPAT; US-PGPUB	2003/12/22 16:50
-	70	((configurable or reconfigurable or re-configurable) near6 pin) and pad and (processor or microprocessor) and (switch or connect\$5 or select\$4)	USPAT; US-PGPUB	2003/12/22 16:50
-	234	(configurable or reconfigurable or re-configurable) near3 pin	USPAT; US-PGPUB	2003/12/22 16:50
-	34	((configurable or reconfigurable or re-configurable) near3 pin) and pad and (processor or microprocessor) and (switch or connect\$5 or select\$4)	USPAT; US-PGPUB	2003/12/22 17:33
-	2289	(257/666,676).CCLS.	USPAT; US-PGPUB	2003/12/22 17:36
-	0	((257/666,676).CCLS.) and ((326/38).CCLS.) and ((326/41).CCLS.) and ((257/e23.011).CCLS.) and ((257/e23.032).CCLS.) and ((257/e23.079).CCLS.) and ((710/316).CCLS.) and ((710/317).CCLS.) and microcontroller	USPAT; US-PGPUB	2003/12/22 17:37
-	142	((257/666,676).CCLS.) or ((326/38).CCLS.) or ((326/41).CCLS.) or ((257/e23.011).CCLS.) or ((257/e23.032).CCLS.) or ((257/e23.079).CCLS.) or ((710/316).CCLS.) or ((710/317).CCLS.)) and microcontroller	USPAT; US-PGPUB	2003/12/22 17:38
-	71	((257/666,676).CCLS.) or ((326/38).CCLS.) or ((326/41).CCLS.) or ((257/e23.011).CCLS.) or ((257/e23.032).CCLS.) or ((257/e23.079).CCLS.) or ((710/316).CCLS.) or ((710/317).CCLS.)) and microcontroller and pad	USPAT; US-PGPUB	2003/12/22 17:39
-	57	((257/666,676).CCLS.) or ((326/38).CCLS.) or ((326/41).CCLS.) or ((257/e23.011).CCLS.) or ((257/e23.032).CCLS.) or ((257/e23.079).CCLS.) or ((710/316).CCLS.) or ((710/317).CCLS.)) and microcontroller and pad and (processor or microprocessor)	USPAT; US-PGPUB	2003/12/22 18:09
-	0	6509758.URPN.	USPAT	2003/12/22 17:50
-	12	("4642561"   "4800294"   "4963768"   "5107146"   "5107230"   "5289116"   "5473758"   "5511182"   "5563526"   "5686844"   "6057705"   "6246258").PN.	USPAT	2003/12/22 17:51
-	14	((((257/666,676).CCLS.) or ((326/38).CCLS.) or ((326/41).CCLS.) or ((257/e23.011).CCLS.) or ((257/e23.032).CCLS.) or ((257/e23.079).CCLS.) or ((710/316).CCLS.) or ((710/317).CCLS.)) and microcontroller and pad) not (((257/666,676).CCLS.) or ((326/38).CCLS.) or ((326/41).CCLS.) or ((257/e23.011).CCLS.) or ((257/e23.032).CCLS.) or ((257/e23.079).CCLS.) or ((710/316).CCLS.) or ((710/317).CCLS.)) and microcontroller and pad and (processor or microprocessor))	USPAT; US-PGPUB	2003/12/22 18:09
-	0	6509758.URPN.	USPAT	2003/12/24 13:48

-	12	("4642561"   "4800294"   "4963768"   "5107146"   "5107230"   "5289116"   "5473758"   "5511182"   "5563526"   "5686844"   "6057705"   "6246258").PN.	USPAT	2003/12/24 13:48
-	12	("4642561"   "4800294"   "4963768"   "5107230"   "5289116"   "5473758"   "5511182"   "5563526"   "5686844"   "5724009"   "6057705"   "6246258").PN.	USPAT	2003/12/24 13:49
-	23	("4472647"   "4698526"   "4877978"   "4896060"   "4902917"   "4930112"   "4978905"   "5084635"   "5144167"   "5153450"   "5157282"   "5161124"   "5162672"   "5300832"   "5309044"   "5345112"   "5353250"   "5359240"   "5402018"   "5406139"   "5600267"   "5732027"   "6047352").PN.	USPAT	2003/12/24 13:50
-	12	("4642561"   "4800294"   "4963768"   "5107146"   "5107230"   "5289116"   "5473758"   "5511182"   "5563526"   "5686844"   "6057705"   "6246258").PN.	USPAT	2003/12/30 13:41
-	0	6509758.URPN.	USPAT	2003/12/30 14:17
-	12	("4642561"   "4800294"   "4963768"   "5107230"   "5289116"   "5473758"   "5511182"   "5563526"   "5686844"   "5724009"   "6057705"   "6246258").PN.	USPAT	2003/12/30 14:17
-	3	("5757207"   "5768598"   "5883526").PN.	USPAT	2003/12/30 17:28
-	0	6188241.URPN.	USPAT	2003/12/30 17:29
-	6	("5701517"   "5715197"   "5737764"   "5748982"   "5822610"   "5835965").PN.	USPAT	2003/12/30 17:29
-	27	"analog circuit" and "digital circuit" and switch and pad and processor and (microcontroller or "micro controller" or micro-controller)	USPAT; US-PGPUB	2003/12/30 17:52
-	0	20020108006.URPN.	USPAT	2003/12/30 17:50
-	0	"analog circuit" and "digital circuit" and switch and pad and processor and (microcontroller or "micro controller" or micro-controller)	EPO; JPO; DERWENT; IBM_TDB	2003/12/30 17:52
-	36	"analog circuit" and "digital circuit" and switch and pad and (processor or microprocessor or cpu) and (microcontroller or "micro controller" or micro-controller)	USPAT; US-PGPUB	2003/12/30 17:53
-	0	6192431.pn. and (analog or digital)	USPAT; US-PGPUB	2004/01/09 12:04
-	1	6192431.pn.	USPAT; US-PGPUB	2004/01/09 13:09
-	883353	(gate or counter or latch\$3 or decoder or encoder or register or flip-flop or "flip flop" or timer) and (filter or amplifier or switch or clipper or limiter or summer or buffer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/09 13:14
-	19576	((gate or counter or latch\$3 or decoder or encoder or register or flip-flop or "flip flop" or timer) and (filter or amplifier or switch or clipper or limiter or summer or buffer)) and microcontroller	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/09 13:15
-	3286	((gate or counter or latch\$3 or decoder or encoder or register or flip-flop or "flip flop" or timer) and (filter or amplifier or switch or clipper or limiter or summer or buffer)) and microcontroller) and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/09 13:15

-	2929	(((((gate or counter or latch\$3 or decoder or encoder or register or flip-flop or "flip flop" or timer) and (filter or amplifier or switch or clipper or limiter or summer or buffer)) and microcontroller) and pad) and (processor or microprocessor))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/09 13:16
-	2581	(((((gate or counter or latch\$3 or decoder or encoder or register or flip-flop or "flip flop" or timer) and (filter or amplifier or switch or clipper or limiter or summer or buffer)) and microcontroller) and pad) and (processor or microprocessor)) and switch\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/09 13:16
-	0	(((((gate or counter or latch\$3 or decoder or encoder or register or flip-flop or "flip flop" or timer) and (filter or amplifier or switch or clipper or limiter or summer or buffer)) and microcontroller) and pad) and (processor or microprocessor)) and switch\$4) and ("selectively connects" near10 pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/09 13:17
-	1325	(((((gate or counter or latch\$3 or decoder or encoder or register or flip-flop or "flip flop" or timer) and (filter or amplifier or switch or clipper or limiter or summer or buffer)) and microcontroller) and pad) and (processor or microprocessor)) and switch\$4) and selectively	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/09 13:18
-	27	(((((gate or counter or latch\$3 or decoder or encoder or register or flip-flop or "flip flop" or timer) and (filter or amplifier or switch or clipper or limiter or summer or buffer)) and microcontroller) and pad) and (processor or microprocessor)) and switch\$4) and "selectively connects"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/09 13:18



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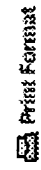
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Wirebond Search Again

**Results:**  
Journal or Magazine = JNL Conference = CNF Standard = STD

1 **Transient three dimensional simulation of mold filling and wire sweep in an overmold BGA package**

Tay, A.A.O.; Lee, W.H.;  
Electronic Components and Technology Conference, 2002. Proceedings. 52nd , 28-31 May 2002  
Page(s): 897 -904

[Abstract] [PDF Full-Text (787 KB)] **IEEE CNF**

2 **Wirebonding: reinventing the process for MCMs**

Charles, H.K. Jr.; Mach, K.J.; Edwards, R.L.; Lehtonen, S.J.; Lee, D.M.;  
Multichip Modules and High Density Packaging, 1998. Proceedings. 1998 7th International Conference on , 15-17 April 1998  
Page(s): 300 -302

[Abstract] [PDF Full-Text (212 KB)] **IEEE CNF**

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3 **A new approach to the robust wirebonding**

Cuong Van Pham; Huth, K.;  
Advanced Packaging Materials: Processes, Properties and Interfaces, 2001.  
Proceedings. International Symposium on , 11-14 March 2001  
Page(s): 379 -385

[Abstract] [PDF Full-Text (852 KB)] **IEEE CNF**

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4 **The effect of wirebond geometry and die setting on wire sweep**

Tay, A.A.O.; Yeo, K.S.; Wu, J.H.;  
Components, Packaging, and Manufacturing Technology, Part B: Advanced Packaging,  
IEEE Transactions on [see also Components, Hybrids, and Manufacturing Technology,  
IEEE Transactions on] , Volume: 18 Issue: 1 , Feb. 1995  
Page(s): 201 -209

[Abstract] [PDF Full-Text (668 KB)] **IEEE JNL**

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5 **Analysis and application of vibration behaviour for wirebonding capillary by transmission laser vibrometer**

Tamura, Y.; Miyahara, Y.; Suzuki, H.;  
Electronics Manufacturing Technology Symposium, 1998. Twenty-Third IEEE/CPMT ,  
19-21 Oct. 1998  
Page(s): 72 -75

[Abstract] [PDF Full-Text (450 KB)] **IEEE CNF**

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6 **High-frequency wirebonding: process and reliability implications**

Charles, H.K., Jr.; Mach, K.J.; Lehtonen, S.J.; Francomacaro, A.S.; DeBoy, J.S.;  
Edwards, R.L.;  
Electronic Components and Technology Conference, 2002. Proceedings. 52nd , 28-31



May 2002

Page(s): 881 -890

[Abstract] [PDF Full-Text (1140 KB)] **IEEE CNF**

7 **Wirebond reliability in IGBT-power modules: application of high resolution strain and temperature mapping**

*Mehrotra, V.; Jun He; Dadkhah, M.S.; Rugg, K.; Shaw, M.C.;*  
Power Semiconductor Devices and ICs, 1999. ISPSD '99. Proceedings., The 11th International Symposium on , 26-28 May 1999  
Page(s): 113 -116

[Abstract] [PDF Full-Text (380 KB)] **IEEE CNF**

8 **Wirebonding Reliability Techniques and Analysis**

*Ebel, G.; Jeffery, J.; Farrell, J.;*  
Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [see also IEEE Trans. on Components, Packaging, and Manufacturing Technology, Part A, B, C] , Volume: 5 Issue: 4 , Dec 1982  
Page(s): 441 -445

[Abstract] [PDF Full-Text (1024 KB)] **IEEE JNL**

9 **DC to 100 GHz chip-to-chip interconnects with reduced tolerance sensitivity by adaptive wirebonding**

*Goebel, U.;*  
Electrical Performance of Electronic packaging, 1994., IEEE 3rd Topical Meeting on , 2-4 Nov. 1994  
Page(s): 182 -185

[Abstract] [PDF Full-Text (276 KB)] **IEEE CNF**

- 10 **The effect of fillet height and bondline thickness on the mechanical performance of a plastic package**  
*Rasihah, I.J.; Breach, C.;*  
Electronic Materials and Packaging, 2000. (EMAP 2000). International Symposium on ,  
30 Nov.-2 Dec. 2000  
Page(s): 416 -420

[Abstract] [PDF Full-Text (368 KB)] **IEEE CNF**

- 11 **Analysis of wirebonding techniques for contacting high concentrator solar cells**  
*Rey-Stolle, I.; Algora, C.;*  
Advanced Packaging, IEEE Transactions on [see also Components, Packaging and  
Manufacturing Technology, Part B: Advanced Packaging, IEEE Transactions on] ,  
Volume: 26 Issue: 1 , Feb. 2003  
Page(s): 47 -53

[Abstract] [PDF Full-Text (357 KB)] **IEEE JNL**

- 12 **A three-dimensional modeling of wire sweep incorporating resin cure**  
*Wu, J.H.; Tay, A.A.O.; Yeo, K.S.; Lim, T.-B.;*  
Components, Packaging, and Manufacturing Technology, Part B: Advanced Packaging,  
IEEE Transactions on [see also Components, Hybrids, and Manufacturing Technology,  
IEEE Transactions on] , Volume: 21 Issue: 1 , Feb. 1998  
Page(s): 65 -72

[Abstract] [PDF Full-Text (208 KB)] **IEEE JNL**

- 13 **Integrated Taguchi method and neural network analysis of physical**

**profiling in the wirebonding process**

*Yu-Lung Lo; Tsao, C.C.;*  
Components and Packaging Technologies, IEEE Transactions on [see also  
Components, Packaging and Manufacturing Technology, Part A: Packaging  
Technologies, IEEE Transactions on] , Volume: 25 Issue: 2 , June 2002  
Page(s): 270 -277

[Abstract] [PDF Full-Text (329 KB)] **IEEE JNL**

**14 Convection modelling of flip chip and wirebond surface mounted modules**

*Yuan, T.D.;*  
Thermal Phenomena in Electronic Systems, 1996. I-THERM V., Inter-Society  
Conference on , 29 May-1 June 1996  
Page(s): 174 -179

[Abstract] [PDF Full-Text (432 KB)] **IEEE CNF**

**15 70 µm fine pitch wirebonding**

*Nguyen, L.; Singh, I.; Murray, C.; Jackson, J.; DeRosa, J.; Ho, D.;*  
Electronics Manufacturing Technology Symposium, 1998. Twenty-Third IEEE/CPMT ,  
19-21 Oct. 1998  
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[Abstract] [PDF Full-Text (1271 KB)] **IEEE CNF**

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